

# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

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## Title of Invention

DESIGN OF BEOL PATTERNS TO REDUCE THE STRESSES  
ON STRUCTURES BELOW CHIP BONDPADS

Application Number :

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Confirmation Number:

First Named Applicant:

Elie Awad

Attorney Docket Number:

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Art Unit: 2818

Examiner:

Search string:

( 4874722 or 5043793 or 5250847 or 5834840 or 5866949 or 5990545 or 6197613  
or 6426545 or 6555908 or 6566244 or 20020011656 ).pn

## US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
TH	1	4874722	1989-10-17	Bednarz et al			
	2	5043793	1991-08-27	Gootzen et al			
	3	5250847	1993-10-05	Baskett			
	4	5834840	1998-11-10	Robbins et al			
	5	5866949	1999-02-02	Schueller			
	6	5990545	1999-11-23	Schueller et al			
	7	6197613	2001-03-06	Kung et al			
	8	6426545	2002-07-30	Eichelberger et al			
	9	6555908	2003-04-29	Eichelberger et al			
TH	10	6566244	2003-05-20	May et al			

## US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
TH	1	20020011656	2002-01-31	Swanson et al			

Signature

TH-TH 10

May 2005